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Return loss at TP2 for CAUI-4 Chip to Module Mike Dudek QLogic Nikhil Patel QLogic March 6 2014



Outline

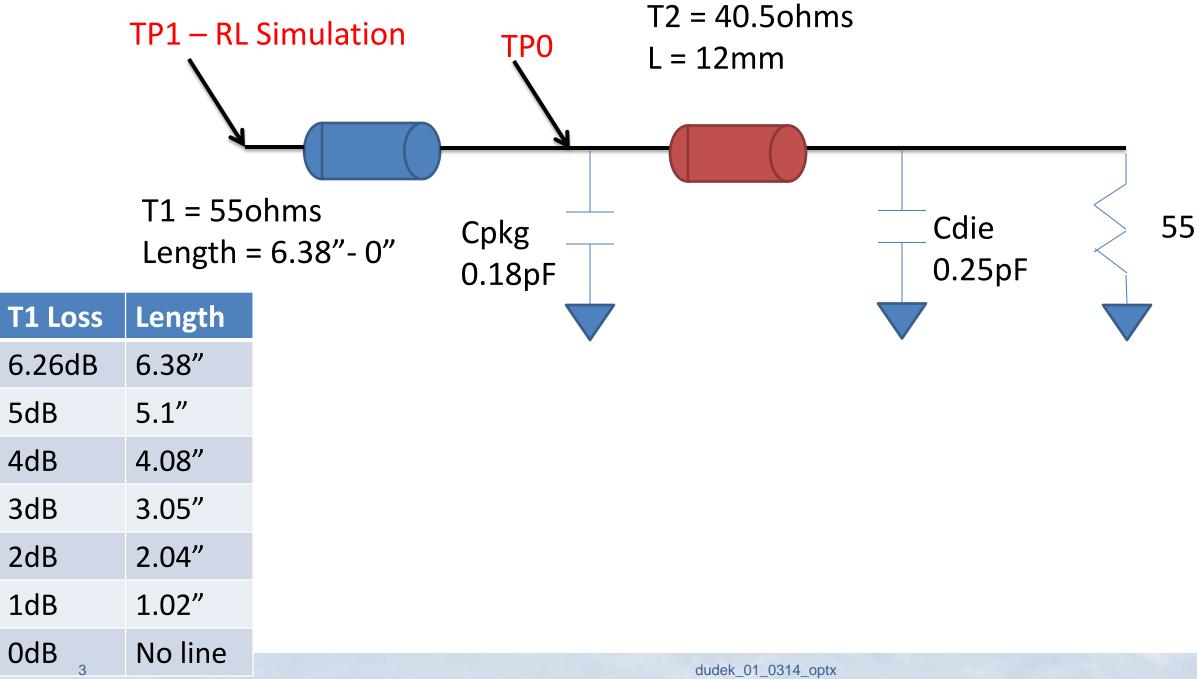
 This presentation investigates the return loss specification at TP2 in 802.3bm draft 2.1 and compares it with the assumed ASIC and host specifications. It is in support of comment 48. A similar comment r01-49 was made against 802.3bj.

The process is as follows.

- 1. A representation of the Clause 93 ASIC model (used in COM calculations) was used for TP0. A representative PCB Tline model was used to get from TP0 to TP1. The length of the transmission line was varied to provide losses that varied from zero to the loss used for the cable calculation in COM. This is to represent hosts with trace lengths with the same loss as the MCB (same as the recommended min loss of the host within <0.1dB at all frequencies) to the recommended max loss of the host.
- 2. Analytical calculations (assuming worst case addition of reflections from the mated MCB/HCB and TP1) were used to generate the return loss at TP2, which are then compared with the clause 83E specification for the host return loss at TP2 (Equation 83E-2). Note that this assumes that the host connector has a return loss no worse than the one used on the MCB.
- 3. In addition S parameters from a measured MCB/HCB were concatenated to get from TP1 to TP2 and these were compared with the clause 83E specification for the host return loss at TP2.



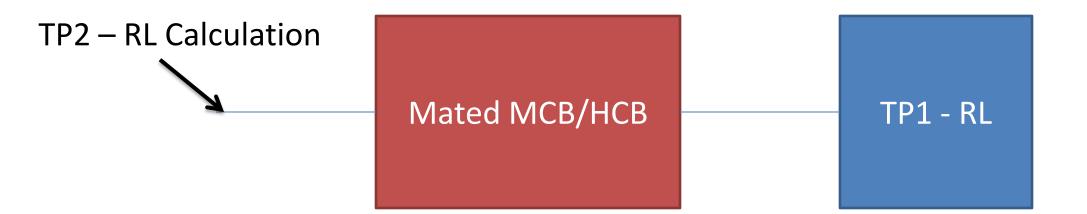
TP1 Simulation setup





55ohms

TP2 Return loss derivation



TP2 RL Equation

TP2 RL = $-20*\log 10(10^{-(MCB_HCB_RL/20)} + 10^{TP1_RL+2*MCB_HCB_IL})/20)$

Term Term22 Num=1 Z=50 Ohm S4F File="F:\NP/	SLIN TL23 Subst="SSub9" C SLIN C14 C=0.18 pF C W=4 mil L=6.38 in C=0.18 pF Subst="SSub7" W=1.000 mil L=12 mm C=0.25 pF ATELVEEE 802.3bjv9114_CD_A1_Mated_TX4.s4p"	Met
Term 23 	$\begin{array}{c} \begin{array}{c} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$	<u>MCB</u> <u>Para</u>
4	dudek_01_0314_optx	

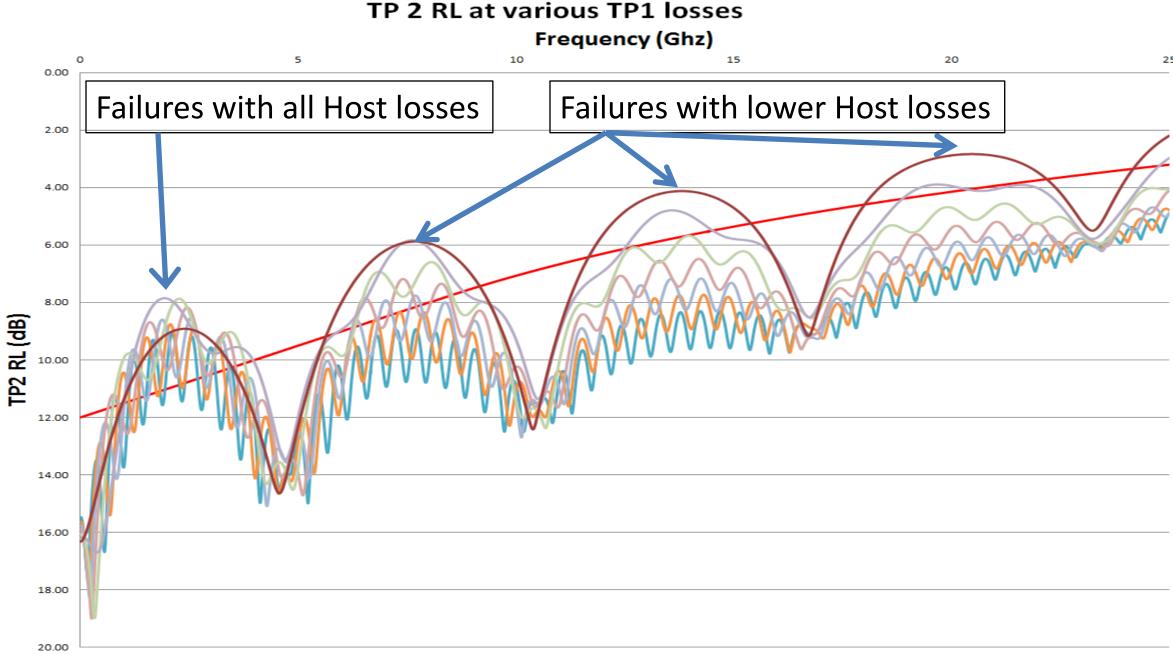


Analytic method

RL – Return Loss IL - Insertion Loss

thod 2 ulation using mated **B/HCB** measured S ameters

TP2 Return Loss – Analytic Method



Host PCB loss is the loss above plus the MCB loss

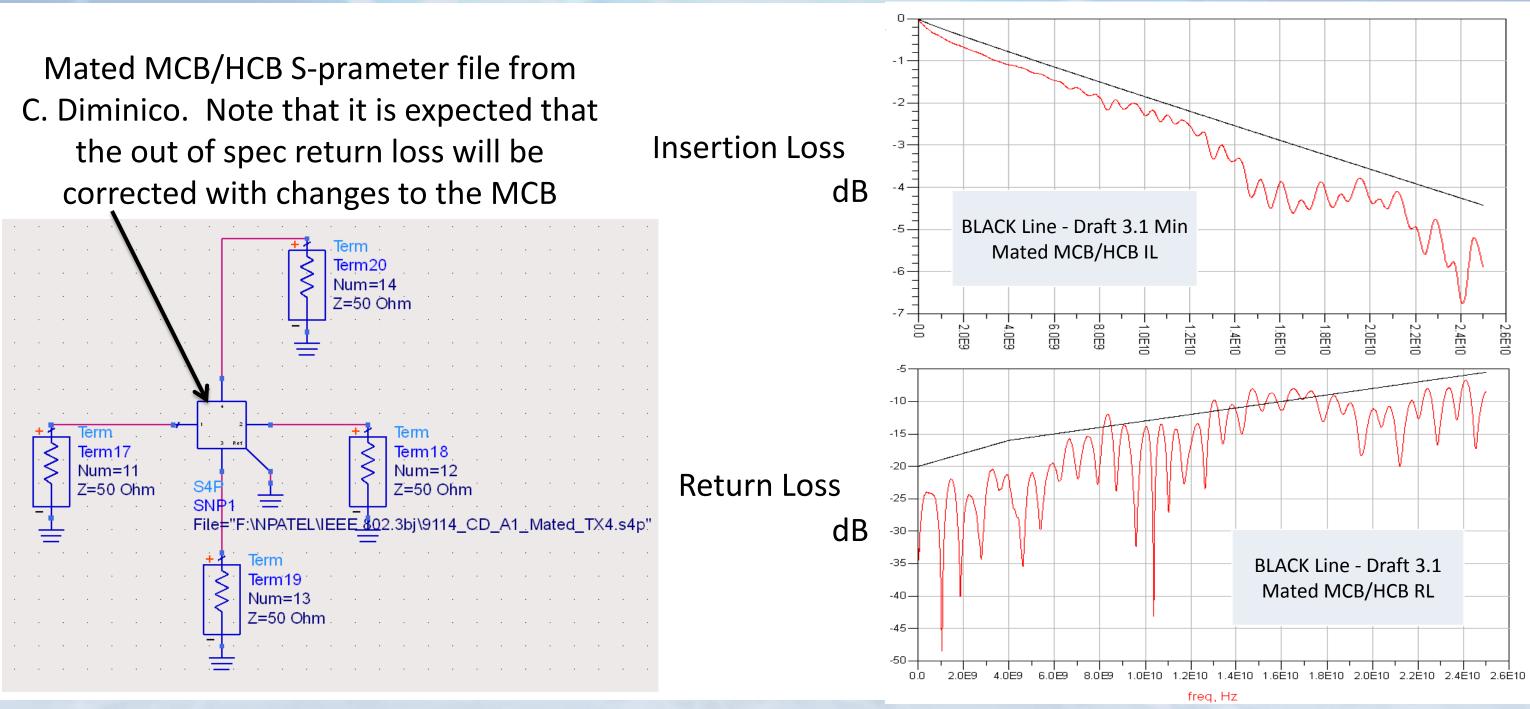
—TP2 - RL @ 4.0dB —TP2 - RL @ 2.0dB

Host RL SPEC

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Mated MCB/HCB S-parameter file

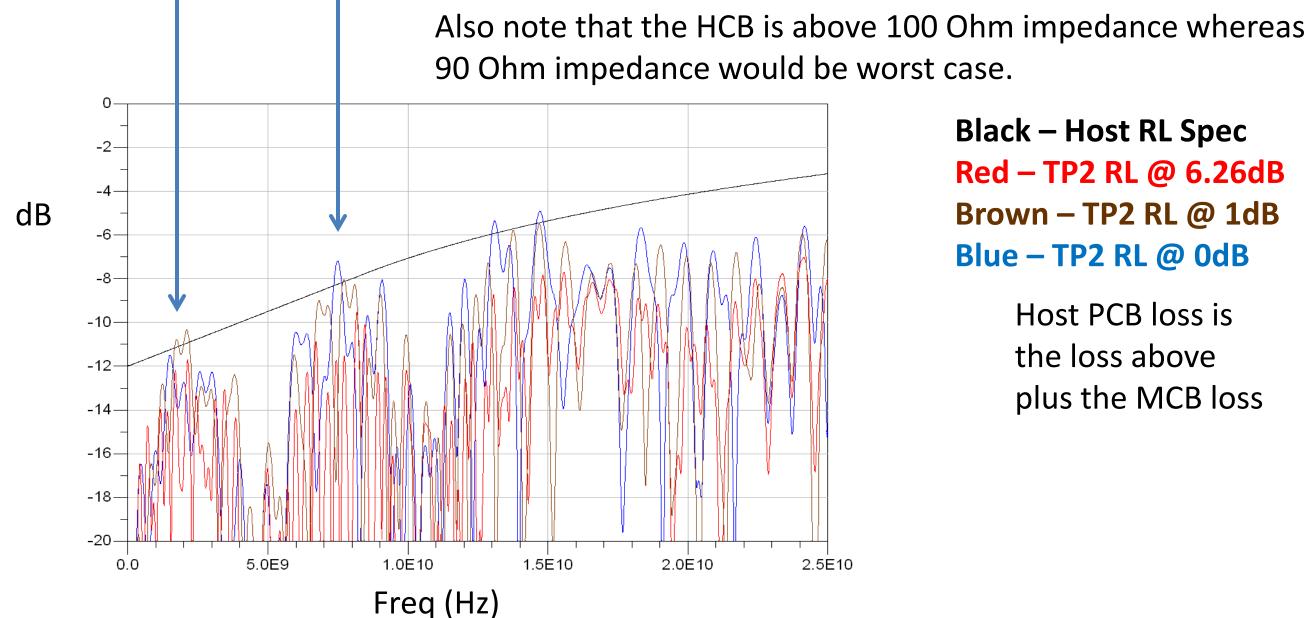


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TP2 Return Loss – Method 2 (measured MCB/HCB)

Fails spec at these frequencies even though HCB/MCB is in spec at these frequencies







Black – Host RL Spec Red – TP2 RL @ 6.26dB Brown – TP2 RL @ 1dB Blue – TP2 RL @ OdB

Host PCB loss is the loss above plus the MCB loss

Conclusions and Proposal

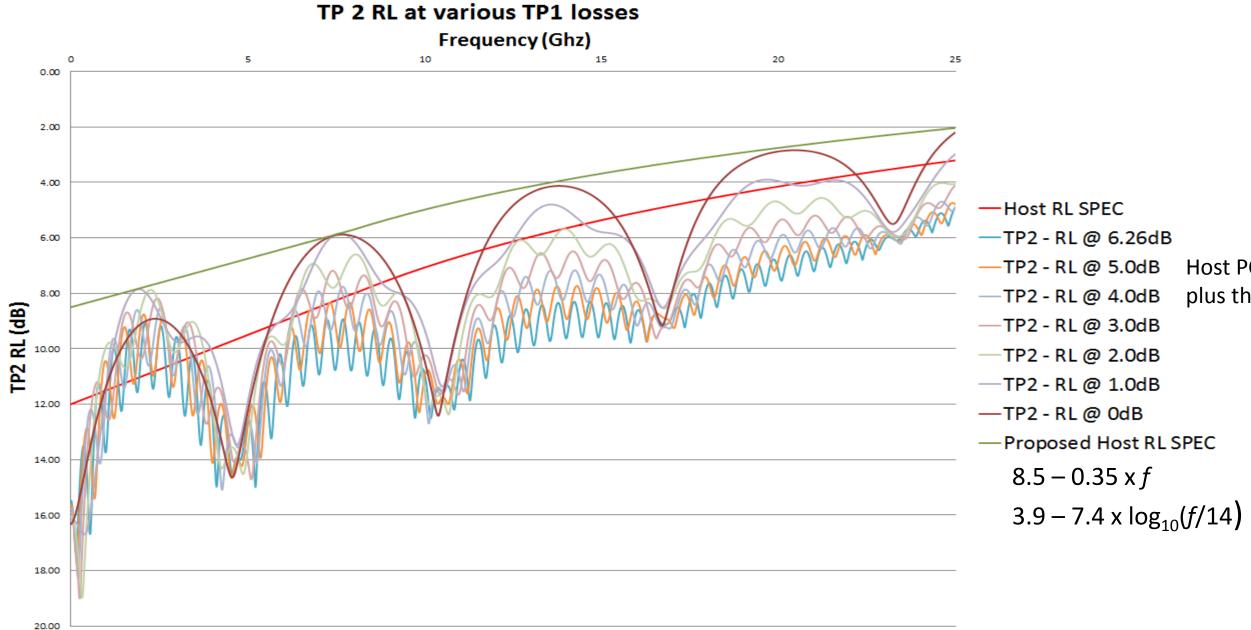
- There is an issue with a worst case Clause 93 IC and assumed host traces. The specification for the return loss at TP2 is not met with compliance boards that just meet their specification
- Proposal
 - 1. As proposed in comment 48 the Host TP2 and TP3 (identical specification in equation 83E-5) should be relaxed to

 $0.01 \le f \le 8$ 8.5 – 0.35 x f $3.9 - 7.4 \times \log_{10}(f/14)$ $8 < f \le 19$

It is not proposed to change the module return loss specifications as it is \bullet expected that the module IC will be a smaller chip that can more easily meet the return loss specifications.



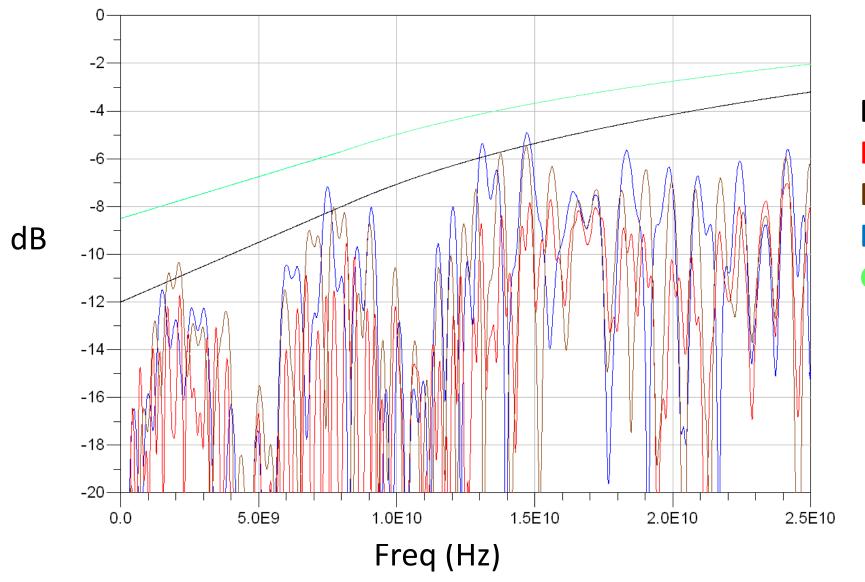
TP2 Return Loss – Analytic Method





DdBHost PCB loss is this lossDdBplus the MCB lossDdBDdBDdBBSt RL SPEC $0.01 \le f \le 8$ $\log_{10}(f/14)$ $8 < f \le 19$

TP2 Return Loss – Method 2



Black – Host RL Spec 8.5 – 0.35 x f



Red – TP2 RL @ 6.26dB + MCB Brown – TP2 RL @ 1dB +MCB Blue – TP2 RL @ 0dB+MCB **Green – Proposed RL Spec** $0.01 \le f \le 8$ $3.9 - 7.4 \times \log_{10}(f/14)$ $8 < f \le 19$



Backup.

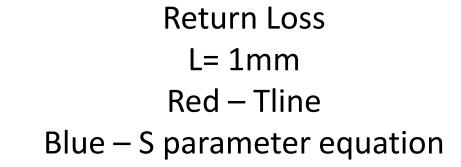


Comparing zp Tline vs S-param equations

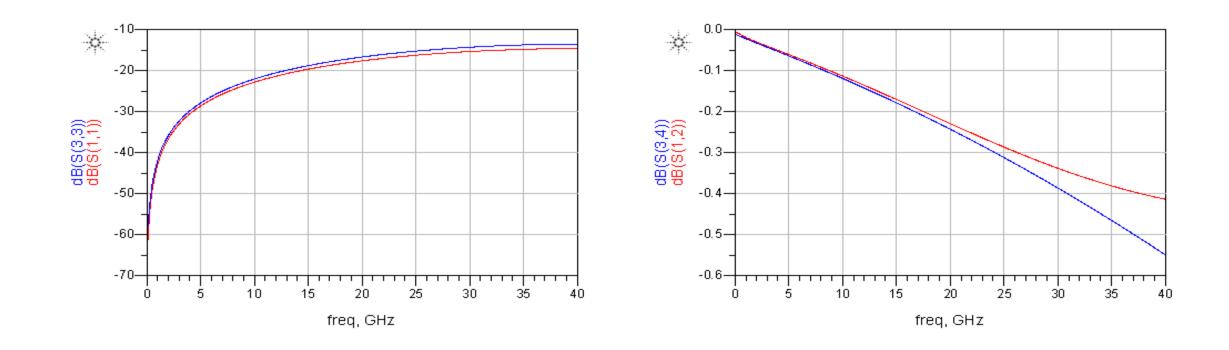
Term SLIN Term3 SLIN Num=1 TL13 Z=50 Ohm Subst="SSub7" VV=1.000 mil L=1 mm	Term Term4 Num=2 Z=50 Ohm S2F	Term Term5 Num=4 Z=50 Ohm
	in a state in 📥 in a state i S2P	219
· · · · · · · · · · · · · · · · · · ·		1]=p0-p1*(1-exp(-j*2*3.142*f*t))
SSub-		2]=exp(y0+y1*sqrt(f)+y2*f+y4*pow(f,2))
	-	1]=exp(y0+y1*sqrt(f)+y2*f+y4*pow(f,2)) 2]=p0-p1*(1-exp(-j*2*3.142*f*t))
SSUB SSUB	Z[1]	
Er=3.3	Z[2]	
Mur=1		
B=60.5 um		
		ar VAR
Cond=5.8e7	Ec	
Tan D=0.02		p0=0.001 y0=-1.067*1e-3
Rough=		p1=0.106 y1=complex(-3.551*1e-4,-3.357*1e-3)
Bbase=		t=1.22e-2 y2=complex(-1.027*1e-3,-3.818*1e-2)
Dpeaks= · · · · · Dpeaks= · · · ·		y4=complex(-1.179*1e-5,3.36*1e-5)
		VAR10
		f=freq/1e9



Comparing zp Tline vs S-param equations

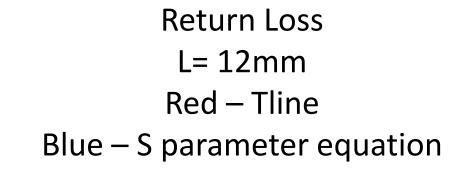


Insertion Loss L=1mmRed – Tline Blue – S parameter equation

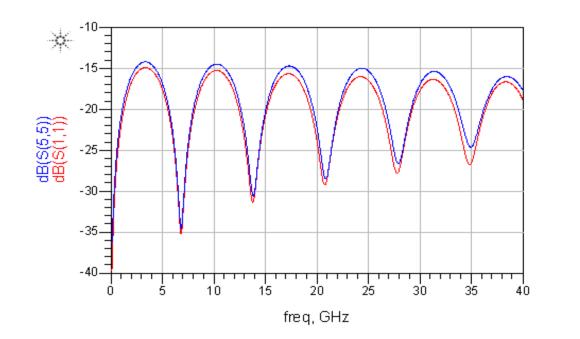


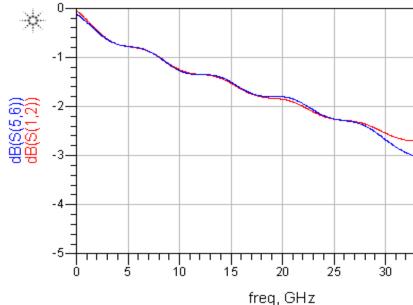


Comparing zp Tline vs S-param equations

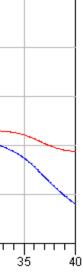


Insertion Loss L= 12mm Red – Tline Blue – S parameter equation



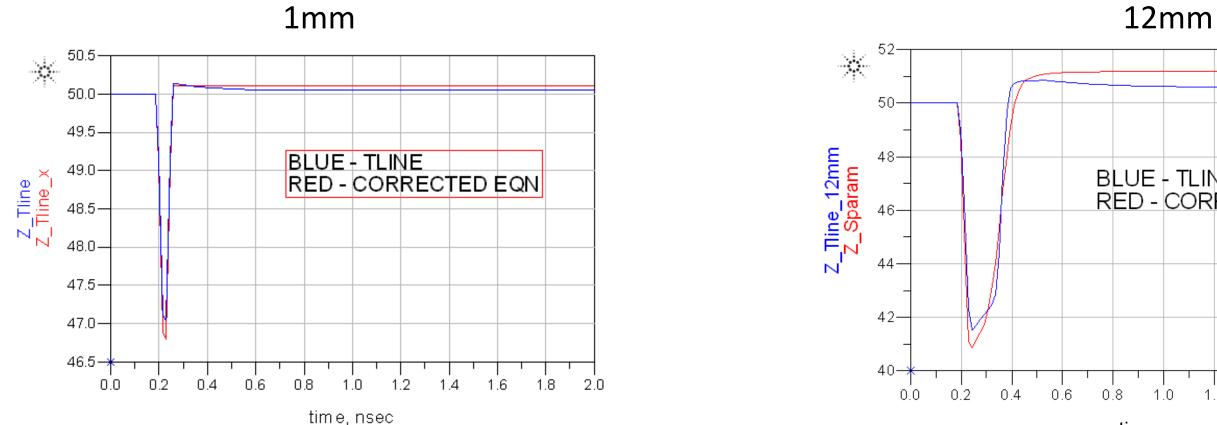






TDR Tline vs. S-param

30ps rise time

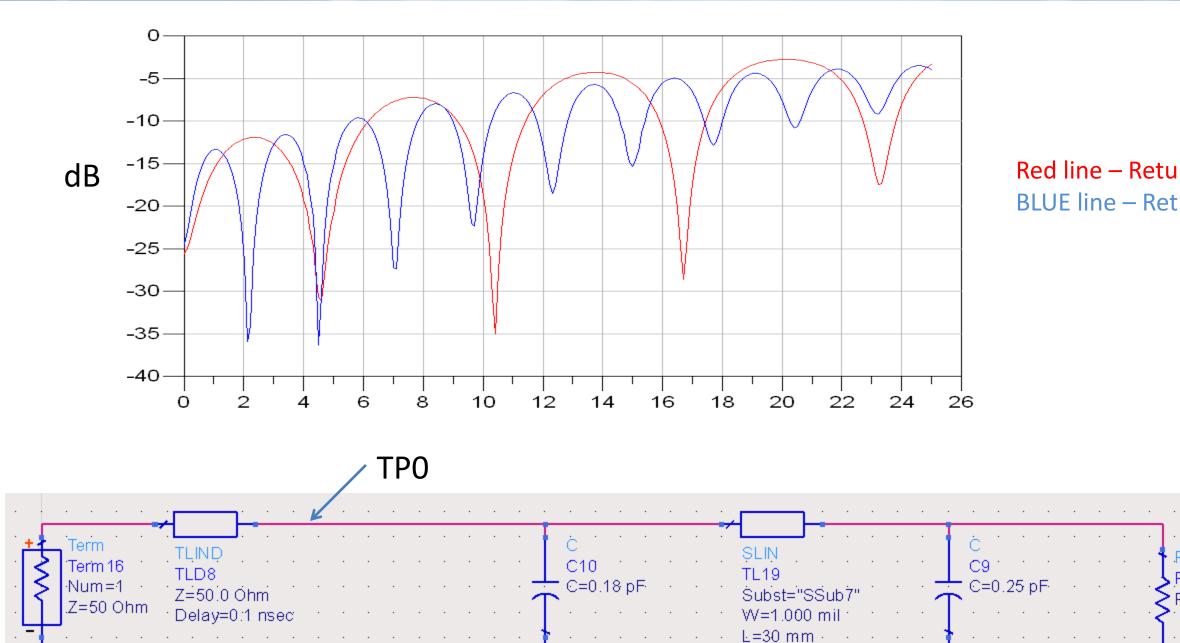


time, nsec





S11 – TP0 – Return loss

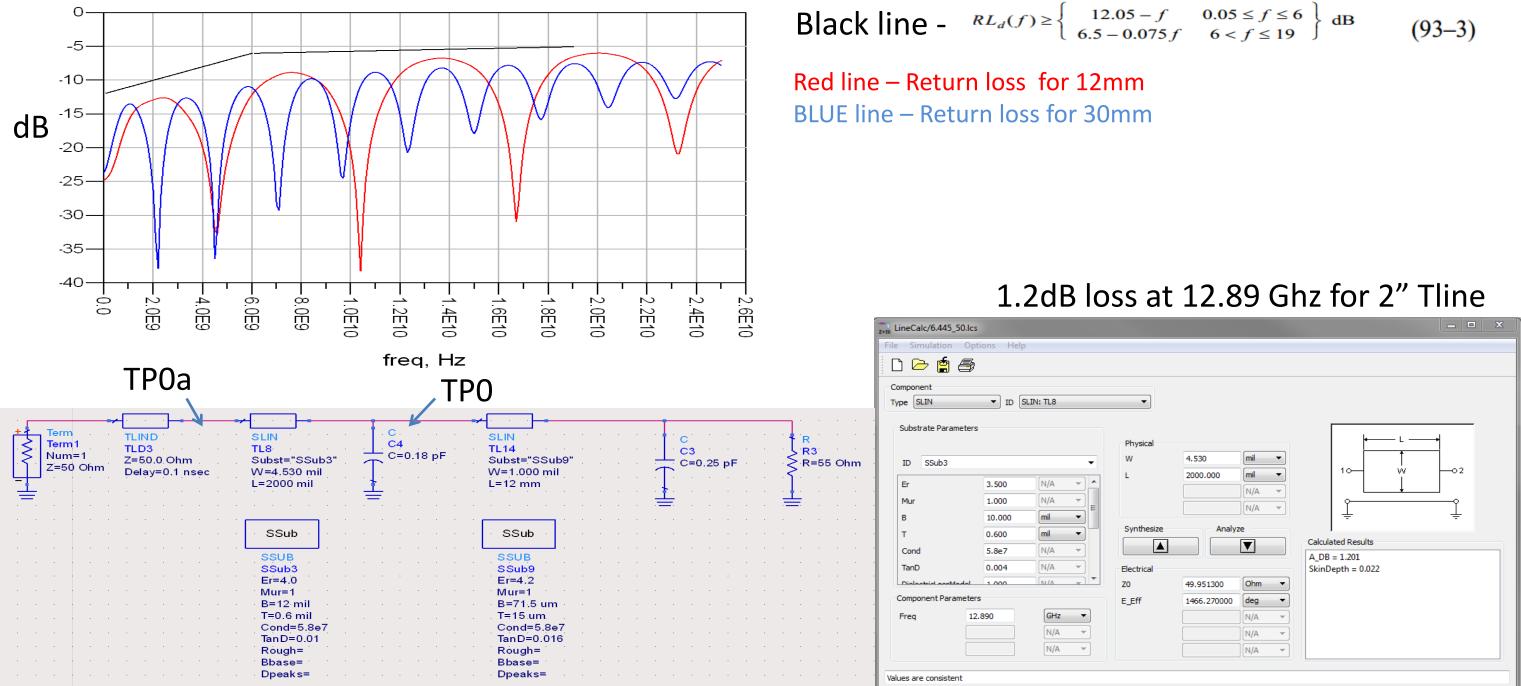




Red line – Return loss for 12mm BLUE line – Return loss for 30mm



S11 – TP0a – Tline test fixture – 50ohms

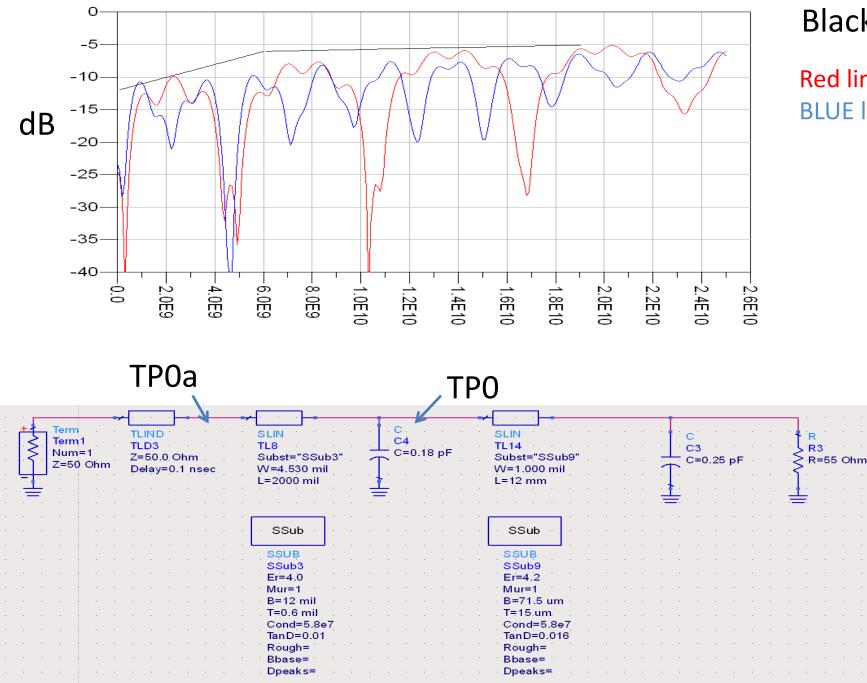


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S11 – TP0a – Tline test fixture – 550hms



Black line - $RL_d(f) \ge \begin{cases} 12.05 - f & 0.05 \le f \le 6 \\ 6.5 - 0.075 f & 6 < f \le 19 \end{cases} dB$

Red line – Return loss for 12mm BLUE line – Return loss for 30mm

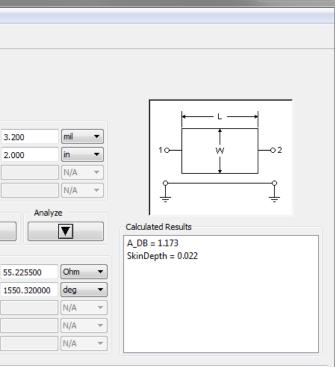


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mponent pe SLIN		GLIN: TL31	
pe SLIN	▼ ID S	LIN; IL31	
Substrate Paramete	rs		
			Physical
ID SSub 10		•	W
Er	3.900	N/A 🔹	L
Mur	1.000	N/A 🔻	
в	10.000	mi 🔹	
т	0.600	mil 🔻	Synthesize
Cond	5.8e7	N/A 🔻	
TanD	0.002	N/A 🔻	Electrical
Dialoctric anoModal	1.000		ZO
Component Paramete	ers		E_Eff
Freq 1	2.890	GHz 🔻	
		N/A 🔻	
		N/A 🔻	



(93-3)

1.2dB loss at 12.89 Ghz for 2" Tline



TP1 Return Loss

TP 1 RL at various Lengths

